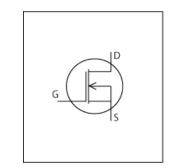


LTspice Model NMOS STM STF26NM60N



Model Information

Model A macro model based on BSIM3 model

Call Name MDC_STF26NM60N_LT

Pin Assign 1:G 2:D 3:S

File List Model Library MDC_STF26NM60N_LT01.lib

Model Report MDC_STF26NM60N_LT.pdf (this file)

Verified Simulator Version

Note

LTspice version XVII

References

The information which was used for modeling is as follow:

[Data Sheet]

Date/Version June 2012Product name STF26NM60N

Company name STMicroelectronics N.V.

Characteristics IdVds[Vgs],IdVgs[Temp],YfsId[Temp],Rds(on)Id[Vgs],VgsQg[

Vdd], Capacitance Vds [Cname], Vth Temp[Id], Rds (on) Temp[Vgs], Vsdls [Temp], Bv Temp[ir], Switching Idd [Tname], Trrlf [Ir], Qrrlf [Ir],

(25degC), TrrQrrWaveform(150degC)

Simulation Range

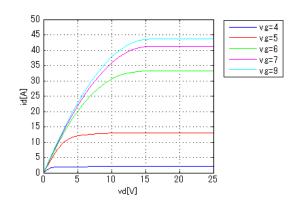
This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

Item	Range			Unit
	Min.		Max.	
Drain-source voltage (DC)	0	to	600	V
Gate-source voltage (DC)	-25	to	25	V
Temperature	-55	to	150	deg C



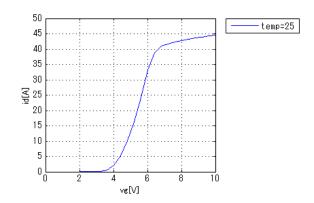
IdVds[Vgs]

Temp. = 25degC

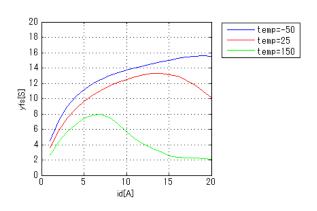


IdVgs[Temp]

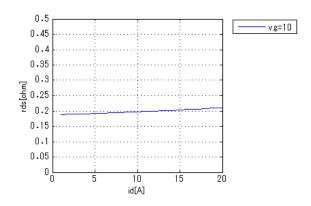
Vds = 25V



YfsId[Temp]

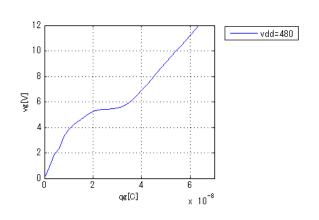


Rds(on)Id[Vgs]



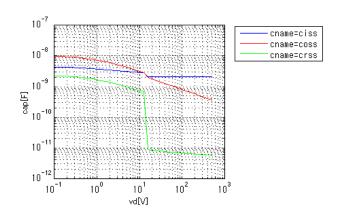
VgsQg[Vdd]

Id = A



CapacitanceVds[Cname]

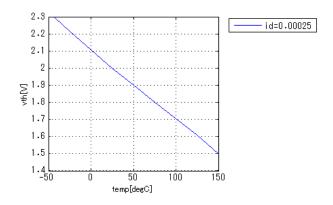
freq = 1000000Hz





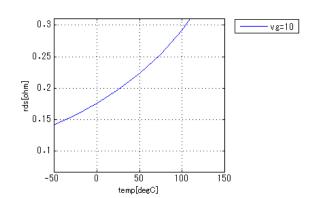
VthTemp[ld]

Vd = Vg



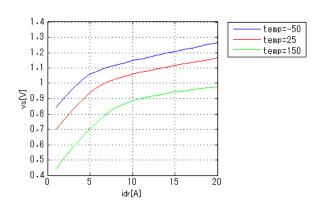
Rds(on)Temp[Vgs]

Id = 10A

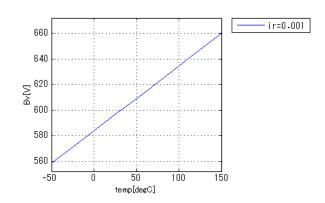


Vsdls[Temp]

vg = 0V

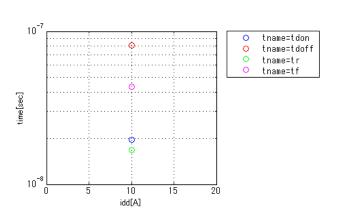


BvTemp[ir]



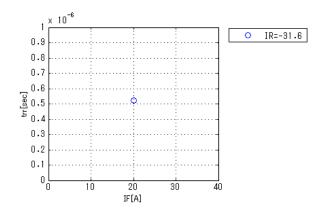
Switchingldd[Tname]

vgg = 10V, vdd = 300V, RGG = 4.70hm



Trrlf[lr]

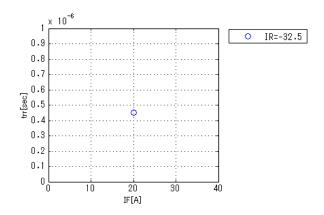
vdd = 60V, didt = 100A/us, Temp = 25degC





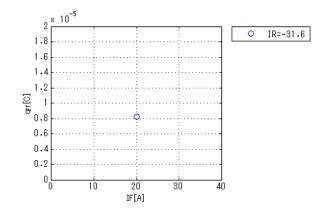
Trrlf[lr]02

vdd = 60V, didt = 100A/us, Temp = 150degC



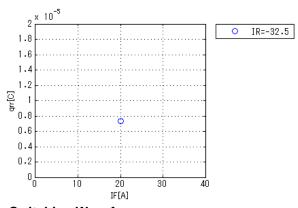
Qrrlf[lr]

vdd = 60V, didt = 100A/us, Temp = 25degC



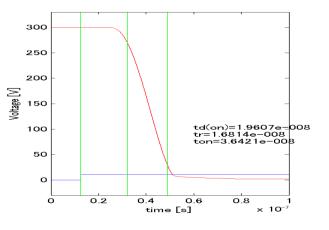
Qrrlf[lr]02

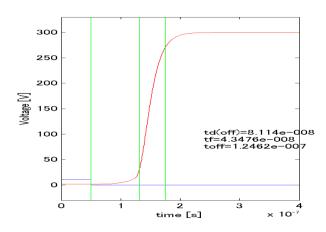
vdd = 60V, didt = 100A/us, Temp = 150degC



Switching Waveform

Blue: INPUT Red: OUTPUT

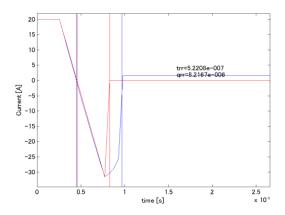






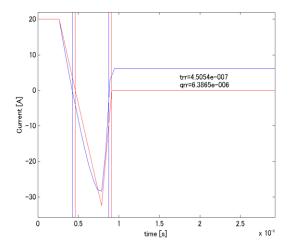
Trr Qrr Waveform (25degC)

Red : Datasheet Blue : Simulation



Trr Qrr Waveform (150degC)

Red : Datasheet Blue : Simulation





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